



Material Content Data Sheet



Halogen-Free

Sales Product Name	BTF3050EJ	Issued	24. June 2021
MA#	MA005549605		
Package	PG-TDSO-8-31	Weight*	67.63 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.016	2.98	2.98	29807	29807
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		140	
	non noble metal	zinc	7440-66-6	0.038	0.06		562	
	non noble metal	iron	7439-89-6	0.760	1.12		11234	
	non noble metal	copper	7440-50-8	30.851	45.62	46.81	456161	468097
wire	non noble metal	copper	7440-50-8	0.380	0.56	0.56	5621	5621
encapsulation	organic material	carbon black	1333-86-4	0.095	0.14		1400	
	plastics	epoxy resin	-	3.691	5.46		54582	
	inorganic material	silicondioxide	60676-86-0	27.765	41.05	46.65	410533	466515
leadfinish	non noble metal	tin	7440-31-5	0.497	0.74	0.74	7352	7352
plating	noble metal	silver	7440-22-4	0.825	1.22	1.22	12195	12195
glue	plastics	epoxy resin	-	0.123	0.18		1822	
	noble metal	silver	7440-22-4	0.581	0.86	1.04	8591	10413
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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